DOCUMENT CHANGE REQUEST

DCR number 302	Changes required for: General	Originator: S JEFFERY
Date: 2006/11/14	Date sent: 2006/11/14	Organisation: ESA/ESTEC
Status: IMPLEMENTED		

Title:	Transistors Low Power PNP, based on type 2N2905A		
Number:	5202/002	Issue:	1

Other documents affected:

Page:

Total re-write

Paragraph:

Total re-write

Original wording:

Proposed wording:

Total reformat of this Detail Specification (under Generic Specification No. 5000) as part of the ongoing conversion to the ESCC format. See below for summary of changes and attached Issue 2 Draft A of the Specification.

Note: known support for active procurement against this specification includes the following manufacturers:

STMICROELECTRONICS/F (ESCC QPL listed with qualified Variants 01 and 02)
SEMELAB/UK (not ESCC qualified but are currently willing to support the procurement of Variants 01 and 02)

Summary of changes to the current format, layout and content is as follows:

1. Rewording and restructure of various sections and paragraphs of the specification plus other editorial changes based on the layout and editorial content of other Detail Specifications already converted to ESCC format (e.g. changes described in DCR No. 203).
2. Deletion of any redundant paragraphs and information, e.g.: Mechanical Requirements.
3. Para. 1.7 High Temperature Test Precautions requirements moved to be a note in the Maximum Ratings table.
4. Deletion of obsolete lead finishes D7, F2 and F4 / Variants 03, 04 and 05 from the available range (not supported by STM or Semelab).
5. Figure 1 Parameter Derating Information moved to be a note in the Maximum Ratings table.
6. Para. 4.3.2 Weight Requirements moved to Component Type Variants table.
7. Figure 2 re-named â..Physical Dimensions and Terminal Identificationâ. and amended to reflect the TO-39 package currently supplied. Notes revised, including addition of a terminal identification note.
8. Para. 4.4.1 Case amended to fully define the TO-39 package.
9. Para. 4.4.2 Lead Material and Finish replaced by a reference to the Component Type Variants Para.
10. Delete requirement for marking of the test level letter from ESCC Component number as per latest ESCC No. 21700.

DOCUMENT CHANGE REQUEST

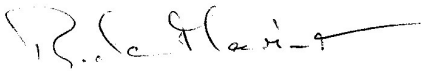
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11. Table 2, Characteristic â..D.C. Forward Current Transfer Ratioâ. has been changed to â..Forward-Current Transfer Ratioâ..
12. Table 2, Characteristic â..A.C. Forward Current Transfer Ratioâ. has been changed to â..Magnitude of Small-Signal Short-Circuit Forward-Current Transfer Ratioâ., Symbol corrected to |hfe| (was hfe) and MIL-STD-750 Test Method corrected to 3306 (was 3206).
13. Table 2: Replace LTPD7 sampling for AC parameters tests (designated by â..Note 2â.) with an equivalent fixed sample of 32 components with 0 failures (or 100%).
14. Table 2 and Figure 4: The Switching Times characteristics have been amended to reflect the new format.
15. Table 3 (High and Low Temperature Electrical Measurements): 100% inspection has been replaced by a sample of 5 components with 0 failures, or 100%, in line with the new Generic 5000 Issue 3.
16. Table 4: Absolute limits have been added for information.
17. Tables 4 and 6, Characteristic â..D.C. Forward Current Transfer Ratioâ. has been changed to â..Forward-Current Transfer Ratio 3â..
18. Tables 2, 3 and 4 - Test Conditions column: addition of Test, or Bias, Conditions for referenced MIL-STD-750 Test Methods as and where applicable.
19. Table 5 â.. Test Conditions for High Temperature Reverse Bias amended: Tamb was +150Â°C, now +150(+0 â..5)Â°C; Duration was 72 hrs, now 72 hours minimum, in line with new Generic 5000 and MIL specifications. Characteristic â..Collector-Base (d.c.)â. re-named â..Collector-Base Voltageâ.. Collector-Base Voltage senses for Burn-In and High Temperature Reverse Bias changed as part is a PNP device (was 40V for Burn-in, now â..40V; was â..50V for HTRB, now 50V).
20. Appendix A for STM added: Note about wafer level pilot lot testing in that AC characteristics during screening may be considered guaranteed but not tested. Note STM is an ESCC QPL listed manufacturer and this device is ESCC qualified; accordingly there is an ESCC approved PID for this device. This amendment is considered technically acceptable on this basis.

Justification:

(see also change details for each item above)

1. Part of the ongoing activity of conversion of cover-sheeted ESA/SCC specifications to the ESCC format.
2. To make the format and presentation consistent with the various other ESCC Detail Specifications already converted to ESCC format.
3. To make the content consistent with ESCC Generic Specification No. 5000 Issue 3.
4. To incorporate specific deviations requested by manufacturer STM within Appendix A which are considered technically acceptable (based on ESCC approved PID for this and other ESCC qualified components manufactured by STM).
5. Update manufacturersâ.. current product availability.
6. To make corrections to technical errors in the previous issue.
7. Standardisation of the TO-39 package in all applicable ESCC detail specs.

Attachments:
5202002_Issue_2_-_Draft_A.pdf, null
Modifications:
Re-number Change Items 11 to 20 as 12 to 21. Add new Change Item 11: Table 2, Test Method for Emitter-Base Breakdown Voltage corrected to 3206 (was 3001).
Approval signature:

Date signed:
2006-11-14

TRANSISTORS, LOW POWER, PNP

BASED ON TYPE 2N2905A

ESCC Detail Specification No. 5202/002

Issue 2 - Draft A	June 2006

Document Custodian: European Space Agency - see https://escies.org

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DOCUMENTATION CHANGE NOTICE

(Refer to https://escies.org for ESCC DCR content)

DCR No.	CHANGE DESCRIPTION
187, TBD	Specification up issued to incorporate editorial and technical changes per DCR.

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1. GENERAL

1.1 SCOPE

This specification details the ratings, physical and electrical characteristics and test and inspection data for the component type variants and/or the range of components specified below. It supplements the requirements of, and shall be read in conjunction with, the ESCC Generic Specification listed under Applicable Documents.

1.2 APPLICABLE DOCUMENTS

The following documents form part of this specification and shall be read in conjunction with it:

(a) ESCC Generic Specification No. 5000
(b) MIL-STD-750, Test Methods and Procedures for Semiconductor Devices

1.3 TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESCC Basic Specification No. 21300 shall apply.

1.4 THE ESCC COMPONENT NUMBER AND COMPONENT TYPE VARIANTS

1.4.1 The ESCC Component Number

The ESCC Component Number shall be constituted as follows:

Example: 520200201

- Detail Specification Reference: 5202002
- Component Type Variant Number: 01 (as required)

1.4.2 Component Type Variants

The component type variants applicable to this specification are as follows:

Variant Number	Based on Type	Case	Lead Material and Finish	Weight max g
01	2N2905A	TO-39	D2	1.2
02	2N2905A	TO-39	D3 or D4	1.2

The lead material and finish shall be in accordance with the requirements of ESCC Basic Specification No. 23500.

1.5 MAXIMUM RATINGS

The maximum ratings shall not be exceeded at any time during use or storage.
Maximum ratings shall only be exceeded during testing to the extent specified in this specification and when stipulated in Test Methods and Procedures of the ESCC Generic Specification.

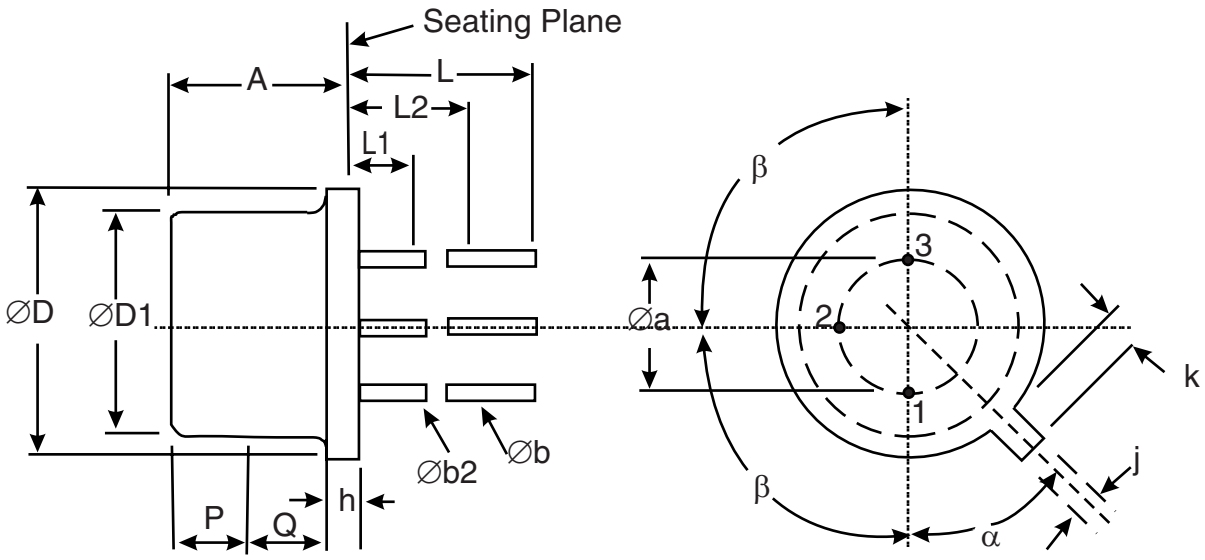
Characteristics	Symbols	Maximum Ratings	Unit	Remarks
Collector-Base Voltage	V_{CBO}	-60	V	Over entire operating temperature range
Collector-Emitter Voltage	V_{CEO}	-60	V	
Emitter-Base Voltage	V_{EBO}	–5	V	
Collector Current	I_C	-600	mA	Continuous
Power Dissipation	P_{tot1}	0.6	W	At $T_{amb} \leq +25^oC$ Note 1
	P_{tot2}	3	W	At $T_{case} \leq +25^oC$ Note 1
Operating Temperature Range	T_{op}	-65 to +200	^oC	Note 2
Storage Temperature Range	T_{stg}	-65 to +200	^oC	Note 2
Soldering Temperature	T_{sol}	+260	^oC	Note 3

NOTES:

1. For T_{amb} or T_{case} > +25°C, derate linearly to 0W at +200°C.
2. For Variants with tin-lead plating or hot solder dip lead finish all testing performed at T_{amb} > +125°C shall be carried out in a 100% inert atmosphere.
3. Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.

1.6 PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION

Metal Can Package (TO-39) - 3 lead



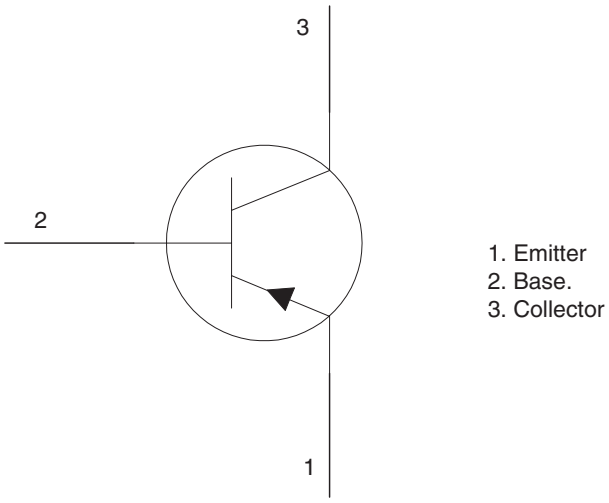
Symbols	Dimensions mm		Notes
	Min	Max	
Øa	4.83	5.35	
A	6	6.6	
Øb	0.4	0.533	2, 3

Symbols	Dimensions mm		Notes
	Min	Max	
Øb2	0.4	0.483	2, 3
ØD	8.31	9.4	
ØD1	7.75	8.51	
h	0.229	3.18	
j	0.71	0.864	
k	0.737	1.14	4
L	12.7	19	2
L1	-	1.27	2, 3
L2	6.35	-	2, 3
P	2.54	-	5
Q	-	-	6
α	45° BSC		1, 7
β	90° BSC		1

NOTES:

1. Terminal identification is specified by reference to the tab position where Lead 1 = emitter, Lead 2 = base and Lead 3 = collector.
2. Applies to all leads.
3. Øb2 applies between L1 and L2. Øb applies between L1 and 12.7mm from the seating plane. Diameter is uncontrolled within L1 and beyond 12.7mm from the seating plane.
4. Measured from the maximum diameter of the actual device.
5. This zone is controlled for automatic handling. The variation in actual diameter within this zone shall not exceed 0.254mm.
6. The details of outline in this zone are optional.
7. Measured from the Tab Centreline.

1.7 FUNCTIONAL DIAGRAM



NOTES:
1. The collector is internally connected to the case.

1.8 MATERIALS AND FINISHES

Materials and finishes shall be as follows:

a) Case
The case shall be hermetically sealed and have a metal body with hard glass seals.
b) Leads
As specified in Component Type Variants.

2. REQUIREMENTS

2.1 GENERAL

The complete requirements for procurement of the components specified herein are as stated in this specification and the ESCC Generic Specification. Permitted deviations from the Generic Specification, applicable to this specification only, are listed below.

Permitted deviations from the Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESCC requirement and do not affect the component's reliability, are listed in the appendices attached to this specification.

2.1.1 Deviations from the Generic Specification

None.

2.2 MARKING

The marking shall be in accordance with the requirements of ESCC Basic Specification No. 21700 and as follows.

The information to be marked on the component shall be:

(a) The ESCC qualified components symbol (for ESCC qualified components only).
(b) The ESCC Component Number.
(c) Traceability information.

2.3 TERMINAL STRENGTH

The test conditions for terminal strength, tested as specified in the ESCC Generic Specification, shall be as follows:

Test Condition: E, lead fatigue.

2.4 ELECTRICAL MEASUREMENTS AT ROOM, HIGH AND LOW TEMPERATURES

Electrical measurements shall be performed at room, high and low temperatures.

2.4.1 Room Temperature Electrical Measurements

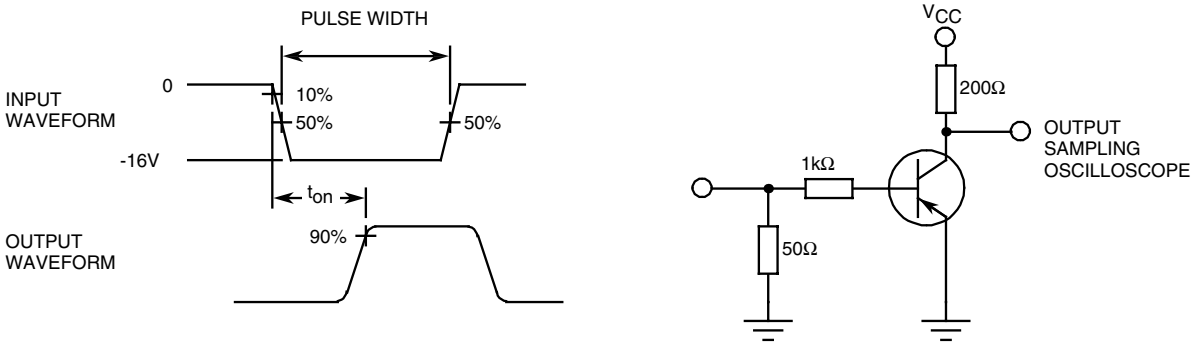
The measurements shall be performed at T_{amb}=+22 ±3°C.

Characteristics	Symbols	MIL-STD-750 Test Method	Test Conditions	Limits		Units
				Min	Max	
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	3001	I_E = -10µA Bias condition D	-60	-	V
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	3011	I_C = -10mA Bias condition D Note 1	-60	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	3026	I_E = -10µA Bias condition D	-5	-	V
Collector-Base Cut-off Current	I_{CBO}	3036	V_{CB} = -50V Bias condition D	-	-10	nA
Forward-Current Transfer Ratio	h_{FE1}	3076	V_{CE}=-10V ; I_C =-100µA	75	-	-
	h_{FE2}	3076	V_{CE}=-10V ; I_C =-1mA	100	-	-
	h_{FE3}	3076	V_{CE}=-10V ; I_C =-150mA Note 1	100	300	-
	h_{FE4}	3076	V_{CE}=-10V ; I_C =-500mA Note 1	50	-	-
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	3071	I_C=-150mA I_B=-15mA Note 1	-	-400	mV
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	3066	I_C=-150mA I_B=-15mA Test condition A Note 1	-	-1.3	V
Magnitude of Small-Signal Short-Circuit Forward-Current Transfer Ratio	$\|h_{fe}\|$	3306	V_{CE}=-20V, I_C=-50mA f=100MHz Note 2	2	-	-
Output Capacitance	C_{obo}	3236	V_{CB}=-10V, I_E=0A 100kHz≤f≤1MHz Note 2	-	8	pF
Turn-on Time	t_{on}	-	V_{CC}=-30V I_C=-150mA I_B=-15mA Notes 2, 3	-	45	ns

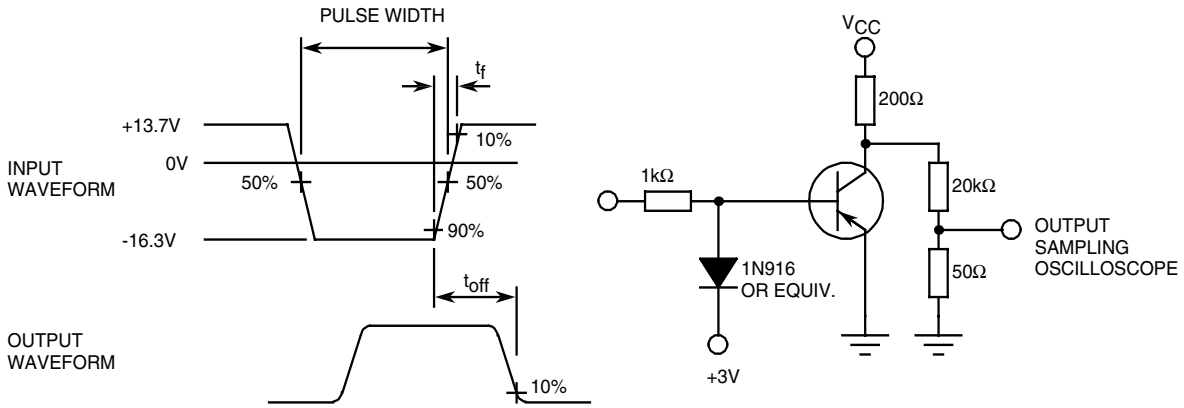
Characteristics	Symbols	MIL-STD-750 Test Method	Test Conditions	Limits		Units
				Min	Max	
Turn-off Time	t_{off}	-	V_{CC}=-30V I_C=-150mA I_B=-15mA Notes 2, 4	-	300	ns

NOTES:

1. Pulse measurement: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%
2. For AC characteristics read and record measurements shall be performed on a sample of 32 components with 0 failures allowed. Alternatively a 100% inspection may be performed.
3. t_{on} shall be measured using the following test circuit. The input waveform shall be supplied by a pulse generator with the following characteristics: Z_{OUT} = 50Ω, t_r ≤ 2ns, Pulse Width = 200 ±10ns, Duty Cycle ≤ 2%. The output waveform shall be monitored on an oscilloscope with the following characteristics: Z_{IN} ≥ 100kΩ, input capacitance ≤ 12pF, t_r ≤ 5ns.



4. t_{off} shall be measured using the following test circuit. The input waveform shall be supplied by a pulse generator with the following characteristics: Z_{OUT} = 50Ω, t_f ≤ 2ns, Pulse Width = 10 to 100µs, Duty Cycle ≤ 2%. The output waveform shall be monitored on an oscilloscope with the following characteristics: Z_{IN} ≥ 100kΩ, input capacitance ≤ 12pF, t_r ≤ 5ns.



2.4.2 High and Low Temperatures Electrical Measurements

Characteristics	Symbols	MIL-STD-750 Test Method	Test Conditions Note 1	Limits		Units
				Min	Max	
Collector-Base Cut-off Current	I_{CBO}	3036	T_{amb}=+150 (+0 -5)˚C V_{CB}=-50V Bias condition D	-	-10	µA

NOTES:
1. Read and record measurements shall be performed on a sample of 5 components with 0 failures allowed. Alternatively a 100% inspection may be performed.

2.5 PARAMETER DRIFT VALUES

Unless otherwise specified, the measurements shall be performed at T_{amb}=+22 ±3°C.

The test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements.

The drift values (Δ) shall not be exceeded for each characteristic specified. The corresponding absolute limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits			Units
		Drift Value Δ	Absolute		
			Min	Max	
Collector-Base Cut-off Current	I_{CBO}	±2 or (1) ±100%	-	-10	nA
Forward-Current Transfer Ratio 3	h_{FE3}	±15%	100	300	-
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	±50 or (1) ±15%	-	-400	mV

NOTES:
1. Whichever is the greater referred to initial value.

2.6 INTERMEDIATE AND END-POINT ELECTRICAL MEASUREMENTS

Unless otherwise specified, the measurements shall be performed at T_{amb}=+22 ±3°C.

The test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements.

The limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits		Units
		Min	Max	
Collector-Base Cut-off Current	I_{CBO}	-	-10	nA
Forward-Current Transfer Ratio 3	h_{FE3}	100	300	-
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	-	-400	mV

2.7 HIGH TEMPERATURE REVERSE BIAS BURN-IN CONDITIONS

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	T_{amb}	+150 (+0 -5)	^{o}C
Collector-Base Voltage	V_{CB}	50	V
Duration	t	72 minimum	Hours

2.8 POWER BURN-IN CONDITIONS

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	T_{amb}	+20 to +50	^{o}C
Power Dissipation	P_{tot}	As per Maximum Ratings P_{tot1} derated at the chosen T_{amb}	W
Collector-Base Voltage	V_{CB}	-40	V

2.9 OPERATING LIFE CONDITIONS

The conditions shall be as specified for Power Burn-in.

APPENDIX 'A'

AGREED DEVIATIONS FOR STMICROELECTRONICS (F)

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS
Deviations from Room Temperature Electrical Measurements	All AC characteristics (Room Temperature Electrical Measurement Note 2) may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes AC characteristic measurements per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.
Deviations from High and Low Temperatures Electrical Measurements	All characteristics specified may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes characteristic measurements at high and low temperatures per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.